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10-31-2000

FORM PTO-1595

U.S. Department of Commerce

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PATENTS ONLY



101501079

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

John W. Orcutt
Andrew Steven Dewa
Tsen-Hwang Lin

Additional name(s) attached? ☐ Yes ☒ No

2. Name and Address of receiving party(ies):

Name: Texas Instruments Incorporated
Address: P.O. Box 655474 M/S 3999
City: Dallas

State: TX Zip: 75265

Additional name(s) attached? ☐ Yes ☒ No

JC675 U.S. PTO
09/67/487
09/27/00

3. Nature of Conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: October 7, 1999, October 21, 1999 and October 22, 1999.

09/67/487

4. Application number(s) or patent number(s).

☒ This document is being filed together with a new application.

Execution date of the application: October 7, 1999.

Title: IMPROVED MEMS WAFER LEVEL PACKAGE.

Docket No.: TI-28230

A. Patent Application No.(s)

Additional numbers attached? ☐ Yes ☒ No

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Gary C. Honeycutt
Navarro IP Law Group, P.C.
801 E. Campbell Rd. Suite 655
Richardson
State: TX Zip: 75081

6. Number of applications and patents involved: 1

7. Amount of fee enclosed or authorized to be charged: \$40

8. Deposit account number (Attach two copies of this form if paying by deposit account): 20-0668

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Gary C. Honeycutt

Date: September 25, 2000

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

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**John W. Orcutt
Andrew Steven Dewa
Tsen-Hwang Lin**

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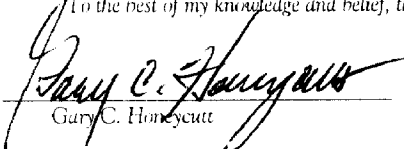
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Gary C. Honeycutt

Date: September 25, 2000

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09/27/00
09/27/00

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and


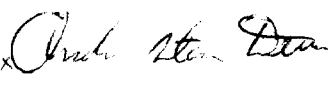
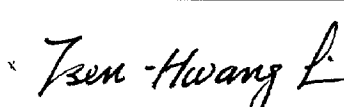
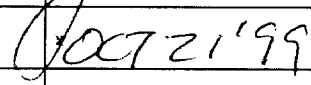
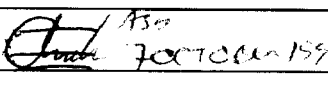
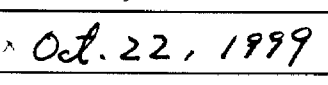
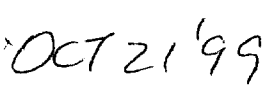
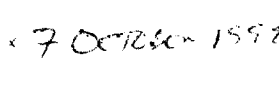
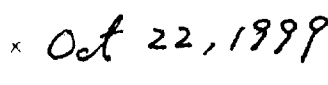
WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with a place of business at 7839 Churchill Way, MS 3999, Dallas, Texas 75251, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year;

TITLE OF INVENTION	Improved MEMS Wafer Level Package		
SIGNATURE OF INVENTOR AND NAME	 John W. Orcutt	 Andrew Steven Dewa	 Tsen-Hwang Lin
DATE OF SIGNATURE	 OCT 21 '99	 OCT 21 '99	 Oct. 22, 1999
RESIDENCE (City, County, State)	Richardson, Dallas County, Texas	Plano, Collin County, Texas	Dallas, Dallas County, Texas
DATE APPLICATION EXECUTED	 OCT 21 '99	 OCT 21 '99	 Oct 22, 1999

After recording Assignment, please return to:

Gary C. Honeycutt
Texas Instruments Incorporated
P.O. Box 655474, MS 3999
Dallas, TX 75265